



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20251014000.1A

**Qualification of an alternate Lead Finish material for select devices
Change Notification / Sample Request**

Date: October 30, 2025

To: MOUSER PCN

Dear Customer:

Revision A is to remove select devices in the Product Affected Section. Those devices were inadvertently added and are not affected by this change.

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

Texas Instruments requires acknowledgement of receipt of this notification within 60 days of the date of this notice. Lack of acknowledgement of this notice within 60 days constitutes acceptance and approval of this change. If samples or additional data are required, requests must be received within 60 days of this notification.

The changes discussed within this PCN will not take effect any earlier than the proposed first ship date on Page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the change management team.

For sample requests or sample related questions, contact your local Field Sales Representative.

TI values customer engagement and feedback related to TI changes. Customers should contact TI if there are questions or concerns regarding a change notification.

Sincerely,

Change Management Team
SC Business Services

20251014000.1A
Change Notification / Sample Request
Attachments

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, you have recently purchased these devices. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
INA213CIRSWR	NULL
DAC53701DSGR	NULL

Technical details of this Product Change follow on the next page(s).

PCN Number:	20251014000.1A			PCN Date:	October 30, 2025								
Title:	Qualification of an alternate Lead Finish material for select devices												
Customer Contact:	Change Management team		Dept:	Quality Services									
Proposed 1st Ship Date:	January 28, 2026		Sample requests accepted until:	December 29, 2025									
*Sample requests received after December 29, 2025 will not be supported.													
Change Type:													
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design	<input type="checkbox"/>	Wafer Bump Material								
<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Data Sheet	<input type="checkbox"/>	Wafer Bump Process								
<input checked="" type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change	<input type="checkbox"/>	Wafer Fab Site								
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Wafer Fab Material								
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process	<input type="checkbox"/>	Wafer Fab Process								
PCN Details													
Description of Change:													
Revision A is to remove devices listed in the Product Affected Section. These devices were inadvertently added and are not affected by this change & will continue to use NiPdAu as lead finish.													
This PCN is to inform of the qualification of an alternate lead finish option for the devices in the product affected section as follows.													
<table border="1" style="width: 100%;"> <thead> <tr> <th></th> <th>Current</th> <th>Additional</th> </tr> </thead> <tbody> <tr> <td>Lead finish</td> <td>NiPdAu</td> <td>Matte Sn</td> </tr> </tbody> </table>							Current	Additional	Lead finish	NiPdAu	Matte Sn		
	Current	Additional											
Lead finish	NiPdAu	Matte Sn											
Reason for Change:													
Continuity of supply													
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):													
None													
Impact on Environmental Ratings:													
Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.													
<table border="1" style="width: 100%;"> <thead> <tr> <th>RoHS</th> <th>REACH</th> <th>Green Status</th> <th>IEC 62474</th> </tr> </thead> <tbody> <tr> <td><input checked="" type="checkbox"/> No Change</td> <td><input checked="" type="checkbox"/> No Change</td> <td><input checked="" type="checkbox"/> No Change</td> <td><input checked="" type="checkbox"/> No Change</td> </tr> </tbody> </table>						RoHS	REACH	Green Status	IEC 62474	<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change
RoHS	REACH	Green Status	IEC 62474										
<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change										
Changes to product identification resulting from this PCN:													
None													
Product Affected:													
TLV755345PDQNR		DAC53701DSGR		TPS7A0525PDQNR									
TLV320ADC3100IRGER		SN74HCS541RKSR		INA213CIRSWR									

Qualification Report

Matte Tin Qualification for WBQFN <=7x7

Approve Date 24-January-2025

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: CC1354P106T0RGZR	Qual Device: OPA2673IRGVR	Qual Device: TMUX7208RUMR	Qual Device: SN003020RTER
UHA	A3	Unbiased HAST	130C/85%RH	96 Hours	3/231/0	3/231/0	3/231/0	3/231/0
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	3/231/0	3/231/0	3/231/0	3/231/0
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	3/231/0	3/231/0	3/231/0	3/231/0
SD	C3	PB-Free Solderability	Precondition w/155C Dry Bake (4 hrs +/- 15 minutes); PB- Free Solder;	-	1/22/0	1/22/0	1/22/0	1/22/0

QBS: Qual By Similarity, also known as Generic Data

Qual Device CC1354P106T0RGZR is qualified at MSL3 260C

Qual Device OPA2673IRGVR is qualified at MSL2 260C

Qual Device TMUX7208RUMR is qualified at MSL1 260C

Qual Device SN003020RTER is qualified at MSL2 260C

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2403-078

Qualification Report

Approve Date 23-MAY -2025

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: TPS51604DSGR-S	Qual Device: ADS8168IRHBR	Qual Device: TPS7A0512PDQNR	Qual Device: INA190A3IRSWR-S	QBS Reference: TUSB546A- DCIRNQR	QBS Reference: ADS8168IRHBR	QBS Reference: DRV8353HRTAR	QBS Reference: INA190A3IRSWR-S
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	-	-	-	-	-	3/231/0	-
UHAST	A3	Autoclave	121C/15psig	96 Hours	-	-	-	-	3/231/0	3/231/0	-	-
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	3/231/0	3/231/0	3/231/0	-	-	-	-	3/231/0
TC	A4	Temperature Cycle	-55C/125C	700 Cycles	3/231/0	3/231/0	3/231/0	-	-	-	-	3/231/0
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	-	-	-	3/231/0	3/231/0	-	-
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	3/231/0	3/231/0	3/231/0	-	3/231/0	3/231/0	-	3/231/0
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes); PB-Free Solder;	-	1/5/0	1/5/0	1/5/0	-	1/22/0	1/22/0	-	1/5/0
PD	C4	Physical Dimensions	(per mechanical drawing)	-	3/60/0	3/60/0	3/60/0	-	-	-	-	-

QBS: Qual By Similarity, also known as Generic Data

Qual Device TPS51604DSGR-S is qualified at MSL1 260C

Qual Device ADS8168IRHBR is qualified at MSL2 260C

Qual Device TPS7A0512PDQNR is qualified at MSL1 260C

Qual Device INA190A3IRSWR-S is qualified at MSL1 260C

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2403-010

Qualification Report

Matte Tin Qualification for UXQFN

Approve Date 23-May-2025

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Attributes	Qual Device: TPD1E10B06DPYR	Qual Device: INA190A3IRSWR-S
Lead Finish	MATTE SN	MATTE SN
Lead Pitch(mm)	0.65	0.4
Mount Compound Supplier	SUMITOMO	FURUKAWA
Mount Compound Supplier Number	CRM-1076NS	AFN603
Mold Compound Supplier	SUMITOMO	SUMITOMO
Mold Compound Supplier Number	EME-G700LTD	EME-G700LTD
Bond Wire Composition	CU	CU
Bond Wire Diameter(um)	20.32	20.32
Flammability Rating	UL 94 V-0	UL 94 V-0

QBS: Qual By Similarity, also known as Generic Data

Qual Device TPD1E10B06DPYR is qualified at MSL1 260C

Qual Device INA190A3IRSWR-S is qualified at MSL1 260C

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>
TI Qualification ID: R-CHG-2403-076

Qualification Report

Matte Tin Qualification for WBQFN <=5x5
Approve Date 18-September-2024

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: TUSB1064RNQR	Qual Device: ADS8166IRHBR	Qual Device: BQ40Z552RSMR
UFAST	A3	Unbiased HAST	130C/85%RH	96 Hours	3/231/0	3/231/0	3/231/0
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	3/231/0	3/231/0	3/231/0
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	3/231/0	3/231/0	3/231/0
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes); PB-Free Solder;	-	1/22/0	1/22/0	1/22/0

QBS: Qual By Similarity, also known as Generic Data

Qual Device TUSB1064RNQR is qualified at MSL1 260C

Qual Device ADS8166IRHBR is qualified at MSL2 260C

Qual Device BQ40Z552RSMR is qualified at MSL2 260C

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2402-114

Qualification Report

Matte Tin Qualification for WBQFN
Approve Date 22-May-2024

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: TUSB546A- DCIRNQR	Qual Device: ADS8168IRHBR	Qual Device: DRV8353HRTAR
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	-	3/231/0
UHAST	A3	Autoclave	121C/15psig	96 Hours	3/231/0	3/231/0	-
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	3/231/0	3/231/0	-
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	3/231/0	3/231/0	-
SD	C3	PB-Free Solderability	Precondition w/155C Dry Bake (4 hrs +/- 15 minutes); PB-Free Solder;	-	1/22/0	1/22/0	-

QBS: Qual By Similarity

Qual Device TUSB546A-DCIRNQR is qualified at MSL1 260C

Qual Device ADS8168IRHBR is qualified at MSL2 260C

Qual Device DRV8353HRTAR is qualified at MSL1 260C

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2309-021

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a 'product qualification family' for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled "QBS Process" (for wafer fab process), "QBS Package" (for assembly process) and "QBS Product" (for product family).

For questions regarding this notice, e-mails can be sent to Change Management team or your local Field Sales Representative.

IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATASHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, or other requirements. These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to TI's Terms of Sale (www.ti.com/legal/termsofsale.html) or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products.